OptiMOS™ - 6 Power-Transistor

AEC Qualified

RoHS

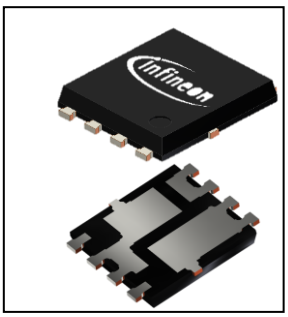
Product Summary

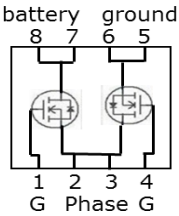
V_{DS}	40	V
$R_{DS(on),max}$	7.0	mΩ
I_D	45	A

Features

- OptiMOS™ - power MOSFET for automotive applications
- Half-Bridge - N-channel - Enhancement mode - Normal Level
- AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green Product (RoHS compliant)
- 100% Avalanche tested

PG-TDSON-8-57





Type	Package	Marking
IAUC45N04S6N070H	PG-TDSON-8-57	6N04N070

Maximum ratings per channel, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Drain current	I_D	V_{GS}=10V, Chip Limitation[1,2)]	48	A
		V_{GS}=10V, DC current[3)]	45	
		T_a=85°C, V_{GS}=10V, R_{thJA} on 2s2p[2,4)]	14	
Pulsed drain current[2)]	$I_{D,pulse}$	T_C=25°C, t_p=100µs	119	
Avalanche energy, single pulse[2)]	E_{AS}	I_D=9A, $R_{g,min}$=25Ω	38	mJ
Avalanche current, single pulse	I_{AS}	$R_{g,min}$=25Ω	9	A
Gate source voltage	V_{GS}	-	±20	V
Power dissipation	P_{tot}	T_C=25°C	41	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics[2]						
Thermal resistance, junction - case	R_{thJC}	-	-	-	3.7	K/W
Thermal resistance, junction - ambient[4]	R_{thJA}	-	-	36	-	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D= 1mA	40	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=9µA	2.2	2.6	3.0	
Zero gate voltage drain current	I_{DSS}	V_{DS}=40V, V_{GS}=0V, T_j=25°C	-	-	1	µA
		V_{DS}=40V, V_{GS}=0V, T_j=125°C[2]	-	-	10	
Gate-source leakage current	I_{GSS}	V_{GS}=20V, V_{DS}=0V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=7V, I_D=22A	-	6.8	9.0	mΩ
		V_{GS}=10V, I_D=22A	-	5.6	7.0	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics[2]						
Input capacitance	C_{iss}	V_{GS}=0V, V_{DS}=25V, f=1MHz	-	539	701	pF
Output capacitance	C_{oss}		-	173	224	
Reverse transfer capacitance	C_{rss}		-	14	21	
Turn-on delay time	$t_{d(on)}$	V_{DD}=20V, V_{GS}=10V, I_D=45A, R_G=3.5Ω	-	3	-	ns
Rise time	t_r		-	1	-	
Turn-off delay time	$t_{d(off)}$		-	4	-	
Fall time	t_f		-	2	-	
Gate Charge Characteristics[2]						
Gate to source charge	Q_{gs}	V_{DD}=32V, I_D=45A, V_{GS}=0 to 10V	-	2.5	3.4	nC
Gate to drain charge	Q_{gd}		-	2.1	3.1	
Gate charge total	Q_g		-	9	12	
Gate plateau voltage	$V_{plateau}$		-	4.7	-	V
Reverse Diode						
Diode continous forward current[2]	I_S	T_C=25°C	-	-	45	A
Diode pulse current[2]	$I_{S,pulse}$	T_C=25°C, t_p=100µs	-	-	119	
Diode forward voltage	V_{SD}	V_{GS}=0V, I_F=22A, T_j=25°C	-	0.85	1.1	V
Reverse recovery time[2]	t_{rr}	V_R=20V, I_F=45A, di_F/dt=100A/µs	-	16	-	ns
Reverse recovery charge[2]	Q_{rr}		-	6	-	nC

[1] Practically the current is limited by overall system design including customer specific PCB.

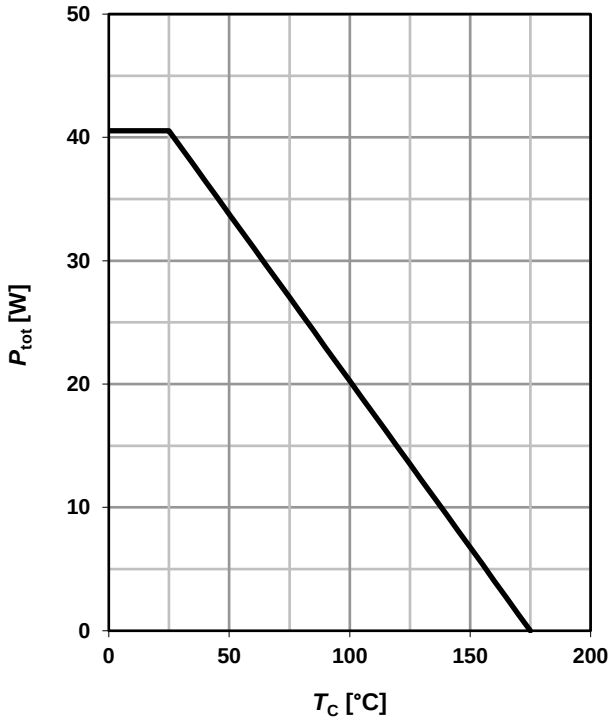
[2] The parameter is not subject to production test -specified by design.

[3] The product can operate at specified current based on best practice to minimize electromigration at the solder joint. For rare events and inrush currents the value may be exceeded.

[4] Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.

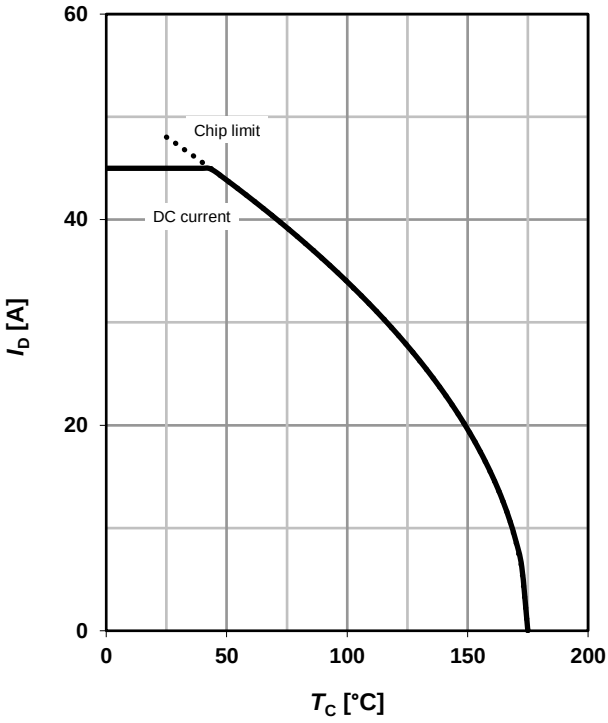
1 Power dissipation

$P_{tot} = f(T_C)$; $V_{GS} = 10$ V



2 Drain current

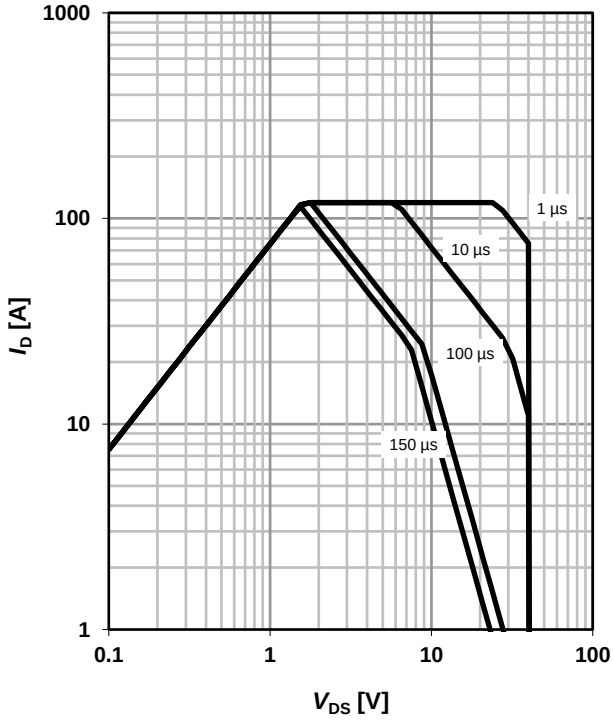
$I_D = f(T_C)$; $V_{GS} = 10$ V



3 Safe operating area

$I_D = f(V_{DS})$; $T_C = 25$ °C; $D = 0$

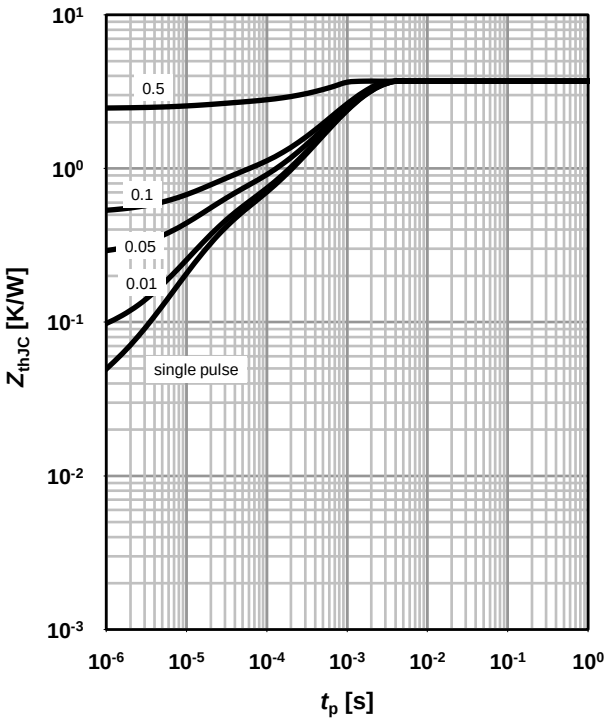
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

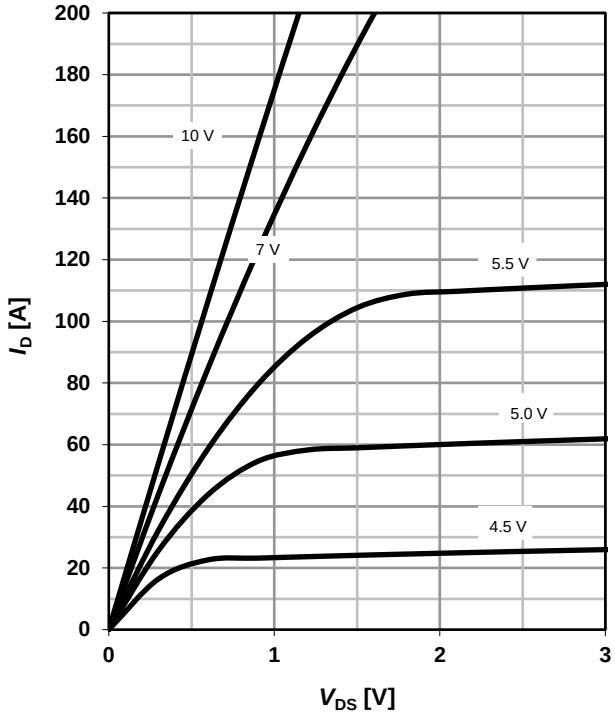
parameter: $D = t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25$ °C

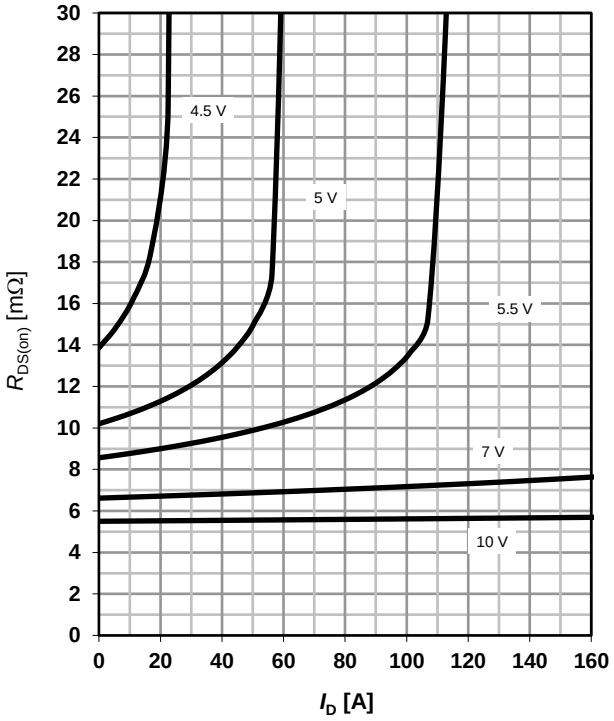
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D)$; $T_j = 25$ °C

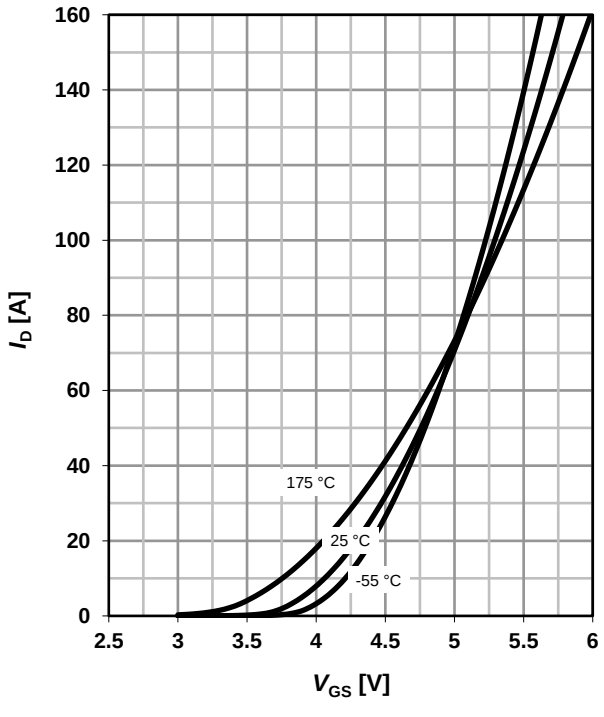
parameter: V_{GS}



7 Typ. transfer characteristics

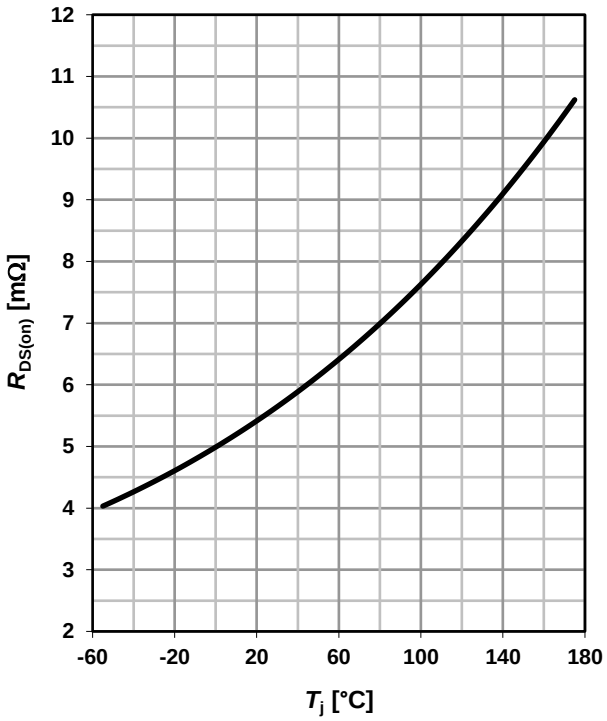
$I_D = f(V_{GS})$; $V_{DS} = 6$V

parameter: T_j



8 Typ. drain-source on-state resistance

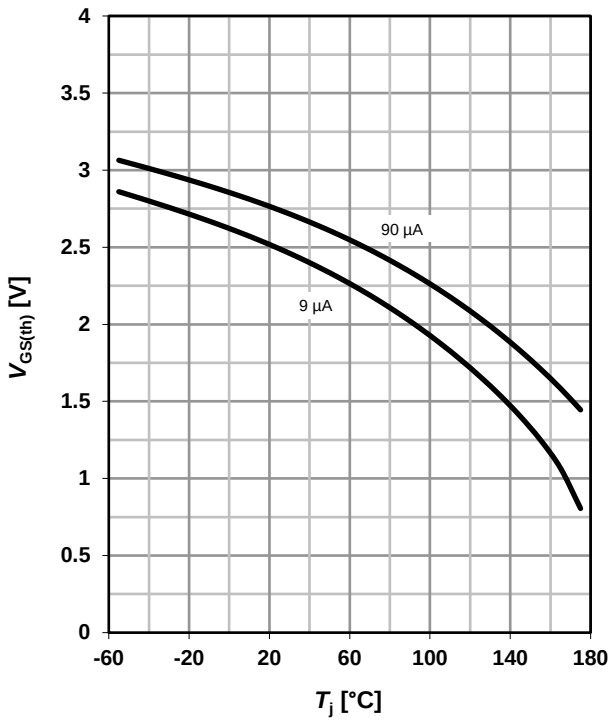
$R_{DS(on)} = f(T_j)$; $I_D = 22$ A; $V_{GS} = 10$ V



9 Typ. gate threshold voltage

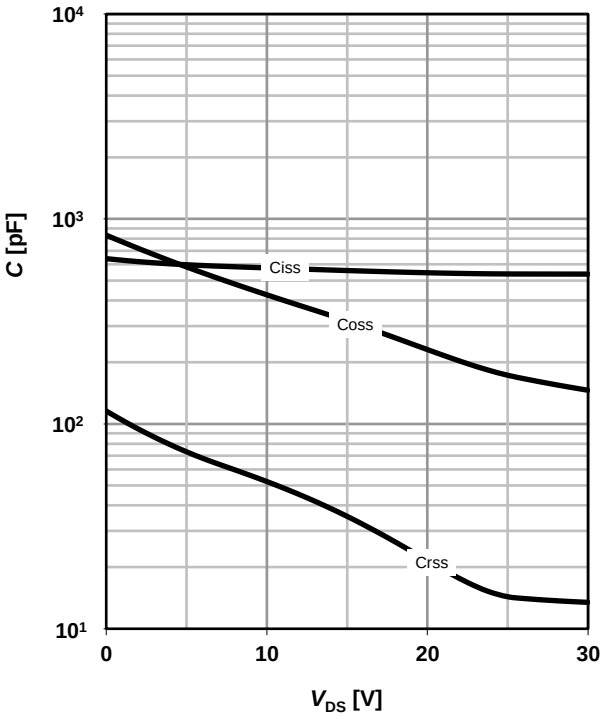
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

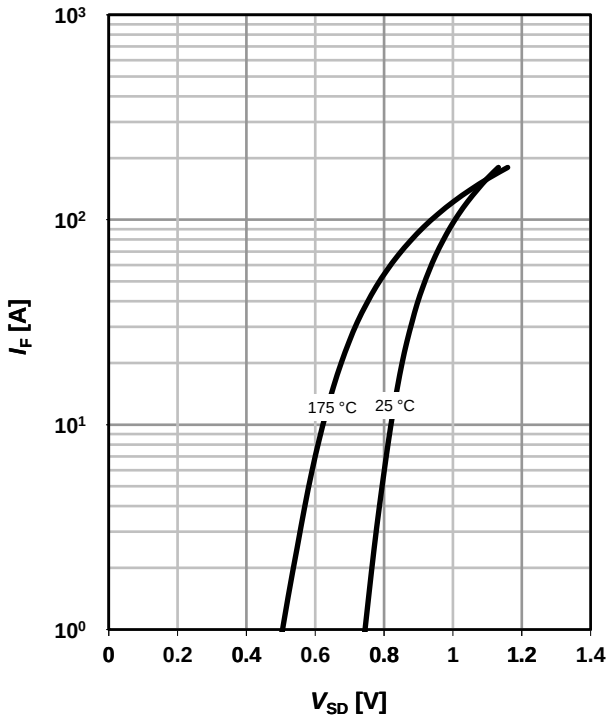
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz



11 Typical forward diode characteristics

IF = f(V_{SD})

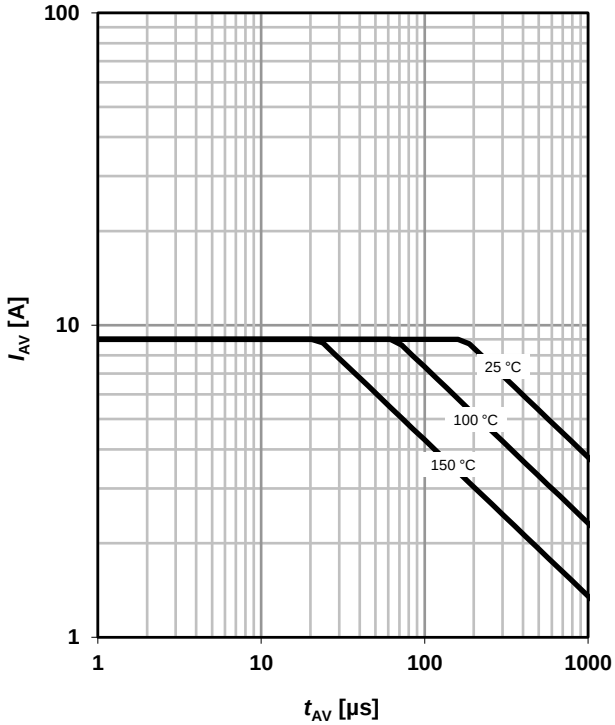
parameter: T_j



12 Avalanche characteristics

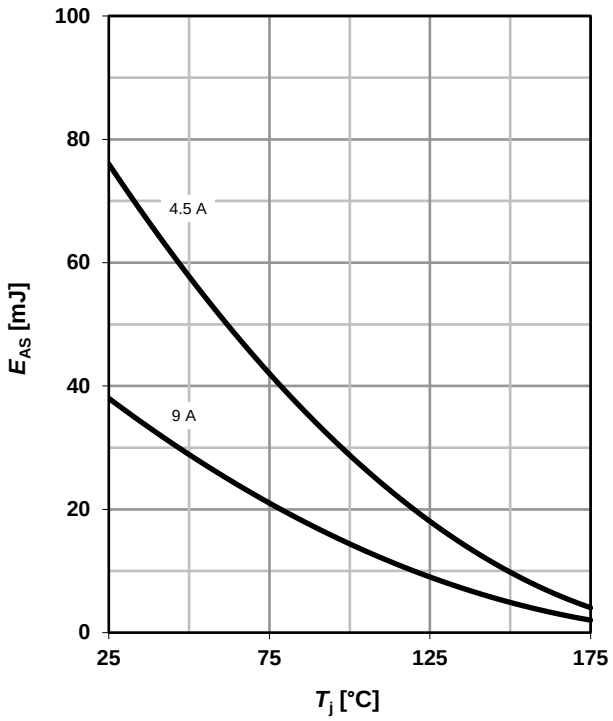
$I_{AS} = f(t_{AV})$

parameter: $T_{j(start)}$



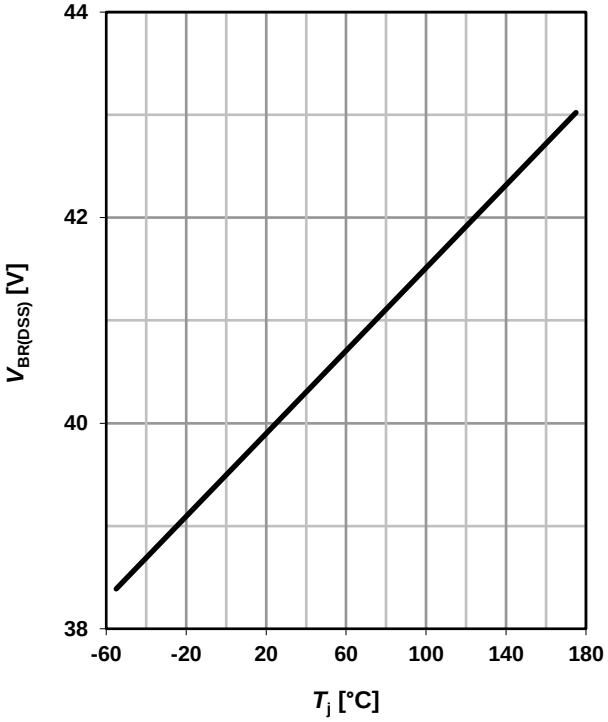
13 Avalanche energy

$E_{AS} = f(T_j)$



14 Drain-source breakdown voltage

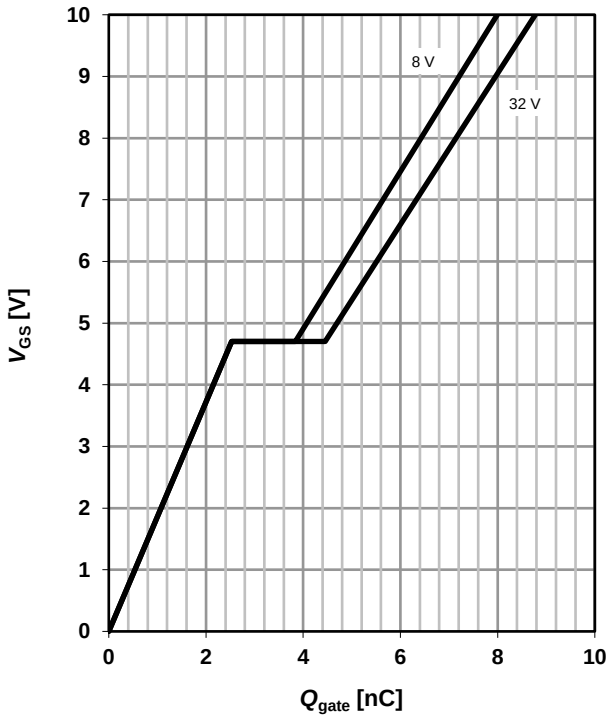
$V_{BR(DSS)} = f(T_j)$; I_D = 1 mA



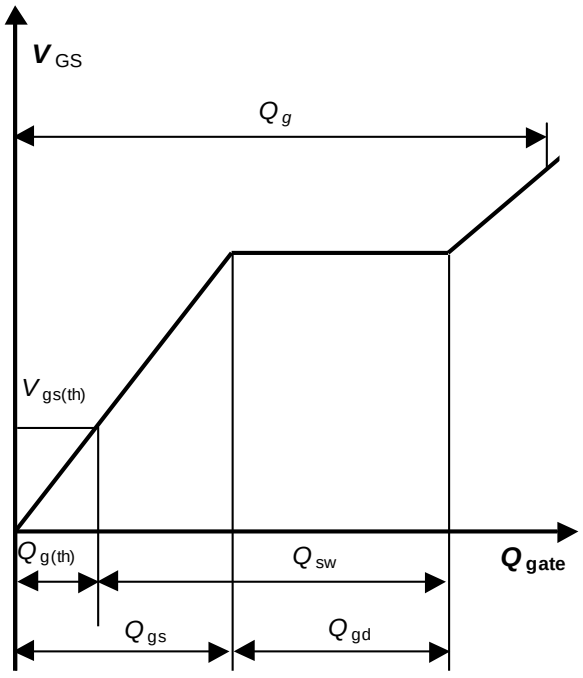
15 Typ. gate charge

$V_{GS} = f(Q_{gate})$; I_D = 45 A pulsed

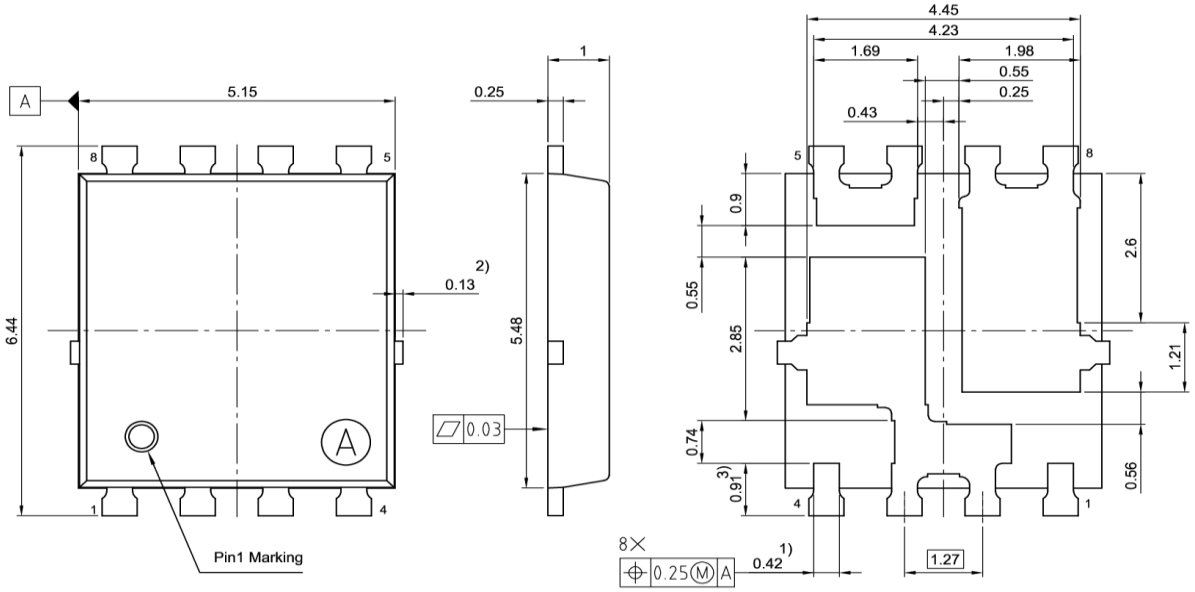
parameter: V_{DD}



16 Gate charge waveforms

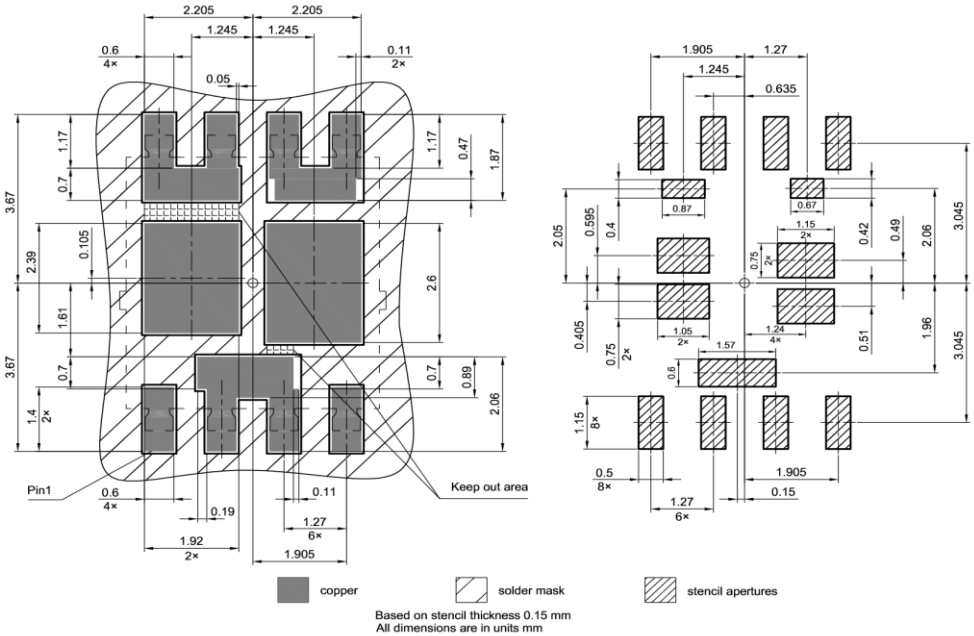


PG-TDSON-8: Outline



1) Excluded mold flash
2) Removal on mold gate: Intrusion 0.1mm, Protrusion 0.1mm
3) Lead length up to anti flash line
All dimensions are in units mm
The drawing is in compliance with ISO 128-30, Projection Method 1 [ ]

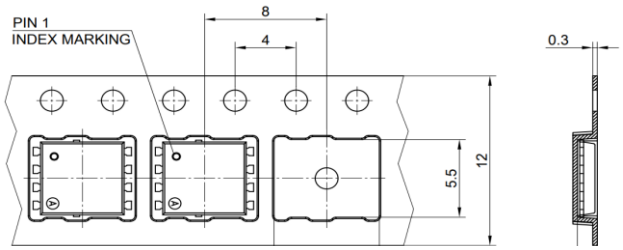
Footprint



Based on stencil thickness 0.15 mm
All dimensions are in units mm

Dimensions in mm

Packaging



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If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Revision History

Version	Date	Changes
Revision 1.0	22.09.2020	Final Datasheet
Revision 1.1	13.02.2025	Update Id chip, Vsd, Is, Is-pulse, plot 2, plot 11, plot 15 - Id condition